COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

+------------------------------+-----------------+-----------------+-----------------+
| PCB VIEWED FROM TOP SIDE     | BOARD #: PMP10478 | REV: A           | SUN REV: Not In VersionControl |
|-------------------------------+-----------------+-----------------+-----------------+
| PLOT NAME = Top Assembly Drawing | GENERATED : 12/1/2014 12:30:18 PM | TEXAS INSTRUMENTS |
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP10478</th>
<th>REV: A</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 12/1/2014 12:30:19 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
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